

**FOR IMMEDIATE RELEASE:**

**Orthodyne Electronics Announces the Shipment of the First *Triple-Head 7600HD Automatic Wedge Bonder System* to a Major Power Semiconductor OEM.**

*Irvine, California –August 2010* - Siegbert Haumann, the Director of Product Marketing – Equipment at Orthodyne states that “The Triple-Head 7600HD Bonder” provides a complete, capacity balanced, in-line solution for bonding PDFN power packages. The bond heads were configured as two *PowerRibbon<sup>®</sup>* heads and one small wire head. *PowerRibbon<sup>®</sup>* is quickly becoming the preferred interconnect choice for small dense PDFN power packages. *PowerRibbon<sup>®</sup>*’s low profile can fit into thin packages. Its large cross-sectional area has a lower resistance and can carry more current than round wire. The advanced leadframe handling and clamping capabilities of the 7600HD leadframe transport system were ideal for the small geometries, high density and complexity of the customer’s PDFN leadframes.”



The 7600HD Automatic Wedge Bonder’s modular and flexible design can be configured in one to four head configurations depending on the line balancing requirements. The system can be easily reconfigured in the field, offering opportunities to rearrange production lines as product mix changes. For added flexibility, each bondhead can accommodate large wire, small wire or *PowerRibbon<sup>®</sup>*.

**About Orthodyne**

Orthodyne Electronics manufactures ultrasonic wire bonders for semiconductor and microelectronic applications. Orthodyne Electronics produces a variety of high production bonders that bond aluminum wire sizes from 1.0 ~ 20mil (25~500 microns) and also bond aluminum *PowerRibbon<sup>®</sup>* (500 x 100 microns to 2000 x 300 microns). Recognized as the industry leader for large aluminum wires and *PowerRibbon<sup>®</sup>*, Orthodyne Electronics has been awarded multiple times for customer satisfaction. ([www.orthodyne.com](http://www.orthodyne.com))

**About Kulicke & Soffa**

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding die and wedge bonders and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. ([www.kns.com](http://www.kns.com))

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